

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-7. (Canceled)

8. (Currently Amended) An audio signal processing circuit comprising:

an operational amplifier formed over an insulating substrate and comprising a thin film element formed over an insulating substrate; element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor; and

a chip capacitor mounted over a flexible printed circuit connected to the insulating substrate, the chip capacitor being electrically connected to the second terminal of the second thin film resistor.

~~wherein one terminal of the thin film resistor is connected to the thin film element and the other terminal of the thin film resistor is connected to the chip capacitor.~~

9. (Currently Amended) The audio signal processing circuit according to claim 8, wherein the audio signal processing circuit comprises an input circuit and the input circuit comprises ~~[[the]]~~ a third thin film resistor and ~~[[the]]~~ a second chip capacitor,

wherein the third thin film resistor and the second chip capacitor are electrically connected to a second input of the operational amplifier.

10. (Currently Amended) The audio signal processing circuit according to claim 8, wherein the audio signal processing circuit comprises a feedback circuit and the feedback circuit comprises the first thin film resistor, the second thin film resistor, and the chip capacitor.

11. (Currently Amended) The audio signal processing circuit according to claim 8, wherein the audio signal processing circuit comprises a smoothing circuit and the smoothing circuit comprises ~~[[the]]~~ a third thin film resistor and ~~[[the]]~~ a second chip capacitor,

wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

12. (Currently Amended) The audio signal processing circuit according to claim 8, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

13. (Currently Amended) The audio signal processing circuit according to claim 8, wherein the first thin film resistor ~~[[has]]~~ and the second thin film resistor have a resistance value of 80 kΩ or more.

14. (Original) An electronic equipment comprising the audio signal processing circuit according to claim 8, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game

machine, a car navigation system, a personal computer and a portable information terminal.

15.-21. (Canceled)

22. (Currently Amended) A display device comprising:

a pixel portion formed over an insulating substrate;

an operational amplifier formed over the insulating substrate and comprising a thin film element formed over an insulating substrate; element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor; and

a chip capacitor mounted around the pixel portion and over the insulating substrate, the chip capacitor being electrically connected to the second terminal of the second thin film resistor.

~~wherein one terminal of the thin film resistor is connected to the thin film element and the other terminal of the thin film resistor is connected to the chip capacitor.~~

23. (Currently Amended) The display device according to claim 22, wherein the display device comprises an input circuit and the input circuit comprises ~~[[the]]~~ a third thin film resistor and [[the]] a second chip capacitor, wherein the third thin film resistor and the second chip capacitor are electrically connected to a second input of the operational amplifier.

24. (Currently Amended) The display device according to claim 22, wherein the display device comprises a feedback circuit and the feedback circuit comprises the first thin film resistor, the second thin film resistor, and the chip capacitor.

25. (Currently Amended) The display device according to claim 22, wherein the display device comprises a smoothing circuit and the smoothing circuit comprises [[the]] a third thin film resistor and [[the]] a second chip capacitor,

wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

26. (Currently Amended) The display device according to claim 22, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

27. (Currently Amended) The display device according to claim 22, wherein the first thin film resistor [[has]] and the second thin film resistor have a resistance value of 80 k Ω or more.

28. (Original) An electronic equipment comprising the display device according to claim 22, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game machine, a car navigation system, a personal computer and a portable information terminal.

29. (Currently Amended) A display device comprising:
a pixel portion formed over an insulating substrate;

an operational amplifier formed over the insulating substrate and comprising a thin film element formed over an insulating substrate; element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor; and

a chip capacitor mounted over a flexible printed circuit connected to the insulating substrate, the chip capacitor being electrically connected to the second terminal of the second thin film resistor.

~~wherein one terminal of the thin film resistor is connected to the thin film element and the other terminal of the thin film resistor is connected to the chip capacitor.~~

30. (Currently Amended) The display device according to claim 29, wherein the display device comprises an input circuit and the input circuit comprises ~~[[the]]~~ a third thin film resistor and [[the]] a second chip capacitor, wherein the third thin film resistor and the second chip capacitor are electrically connected to a second input of the operational amplifier.

31. (Currently Amended) The display device according to claim 29, wherein the display device comprises a feedback circuit and the feedback circuit comprises the first thin film resistor, the second thin film resistor, and the chip capacitor.

32. (Currently Amended) The display device according to claim 29, wherein the display device comprises a smoothing circuit and the smoothing circuit comprises [[the]] a third thin film resistor and [[the]] a second chip capacitor,

wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

33. (Currently Amended) The display device according to claim 29, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

34. (Currently Amended) The display device according to claim 29, wherein the first thin film resistor [[has]] and the second thin film resistor have a resistance value of 80 k Ω or more.

35. (Original) An electronic equipment comprising the display device according to claim 29, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game machine, a car navigation system, a personal computer and a portable information terminal.

36.-42. (Canceled)

43. (New) The audio signal processing circuit according to claim 8, wherein the audio signal processing circuit comprises an input circuit and the input circuit comprises the second thin film resistor and the chip capacitor.

44. (New) The display device according to claim 22, wherein the display device comprises an input circuit and the input circuit comprises the second thin film resistor and the chip capacitor.

45. (New) The display device according to claim 29, wherein the display device comprises an input circuit and the input circuit comprises the second thin film resistor and the chip capacitor.

46. (New) An audio signal processing circuit comprising:

an operational amplifier formed over an insulating substrate and comprising a thin film element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor; and

a chip capacitor mounted over the insulating substrate, the chip capacitor being electrically connected to the second terminal of the second thin film resistor.

47. (New) The audio signal processing circuit according to claim 46, wherein the audio signal processing circuit comprises an input circuit and the input circuit comprises a third thin film resistor and a second chip capacitor, wherein the third thin film resistor and the second chip capacitor are electrically connected to a second input of the operational amplifier.

48. (New) The audio signal processing circuit according to claim 46, wherein the audio signal processing circuit comprises an input circuit and the input circuit comprises the second thin film resistor and the chip capacitor.

49. (New) The audio signal processing circuit according to claim 46, wherein the audio signal processing circuit comprises a feedback circuit and the feedback circuit comprises the first thin film resistor, the second thin film resistor, and the chip capacitor.

50. (New) The audio signal processing circuit according to claim 46, wherein the audio signal processing circuit comprises a smoothing circuit and the smoothing circuit comprises a third thin film resistor and a second chip capacitor,

wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

51. (New) The audio signal processing circuit according to claim 46, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

52. (New) The audio signal processing circuit according to claim 46, wherein the first thin film resistor and the second thin film resistor have a resistance value of 80 k Ω or more.

53. (New) An electronic equipment comprising the audio signal processing circuit according to claim 46, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game machine, a car navigation system, a personal computer and a portable information terminal.

54. (New) An audio signal processing circuit comprising:

an operational amplifier formed over an insulating substrate and comprising a thin film element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor; and

a chip capacitor mounted over a printed circuit board electrically connected to the insulating substrate, the chip capacitor being electrically connected to the second terminal of the second thin film resistor.

55. (New) The audio signal processing circuit according to claim 54, wherein the audio signal processing circuit comprises an input circuit and the input circuit comprises a third thin film resistor and a second chip capacitor, wherein the third thin film resistor and the second chip capacitor are electrically connected to a second input of the operational amplifier.

56. (New) The audio signal processing circuit according to claim 54, wherein the audio signal processing circuit comprises an input circuit and the input circuit comprises the second thin film resistor and the chip capacitor.

57. (New) The audio signal processing circuit according to claim 54, wherein the audio signal processing circuit comprises a feedback circuit and the feedback circuit comprises the first thin film resistor, the second thin film resistor, and the chip capacitor.

58. (New) The audio signal processing circuit according to claim 54, wherein the audio signal processing circuit comprises a smoothing circuit and the smoothing circuit comprises a third thin film resistor and a second chip capacitor,

wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

59. (New) The audio signal processing circuit according to claim 54, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

60. (New) The audio signal processing circuit according to claim 54, wherein the first thin film resistor and the second thin film resistor have a resistance value of 80 k Ω or more.

61. (New) An electronic equipment comprising the audio signal processing circuit according to claim 54, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game machine, a car navigation system, a personal computer and a portable information terminal.

62. (New) A display device comprising:
a pixel portion formed over an insulating substrate;

an operational amplifier formed over the insulating substrate and comprising a thin film element, the operational amplifier including an input terminal and an output terminal;

a first thin film resistor formed over the insulating substrate, a first terminal of the first thin film resistor being electrically connected to the input terminal of the operational amplifier, and a second terminal of the first thin film resistor being electrically connected to the output terminal of the operational amplifier;

a second thin film resistor formed over the insulating substrate, a first terminal of the second thin film resistor being electrically connected to the input terminal of the operational amplifier and the first terminal of the first thin film resistor; and

a chip capacitor mounted over a printed circuit board electrically connected to the insulating substrate, the chip capacitor being electrically connected to the second terminal of the second thin film resistor.

63. (New) The display device according to claim 62, wherein the display device comprises an input circuit and the input circuit comprises a third thin film resistor and a second chip capacitor, wherein the third thin film resistor and the second chip capacitor are electrically connected to a second input of the operational amplifier.

64. (New) The display device according to claim 62, wherein the display device comprises an input circuit and the input circuit comprises the second thin film resistor and the chip capacitor.

65. (New) The display device according to claim 62, wherein the display device comprises a feedback circuit and the feedback circuit comprises the first thin film resistor, the second thin film resistor, and the chip capacitor.

66. (New) The display device according to claim 62, wherein the display device comprises a smoothing circuit and the smoothing circuit comprises a third thin film resistor and a second chip capacitor,

wherein a first terminal of the third thin film resistor is electrically connected to the first thin film resistor, and

wherein a second terminal of the third thin film resistor is connected to the second chip capacitor.

67. (New) The display device according to claim 62, wherein P-type impurities are doped in the first thin film resistor and the second thin film resistor.

68. (New) The display device according to claim 62, wherein the first thin film resistor and the second thin film resistor have a resistance value of 80 k Ω or more.

69. (New) An electronic equipment comprising the display device according to claim 62, wherein the electronic equipment is one selected from the group consisting of a video camera, a digital camera, a head mounted display, a game machine, a car navigation system, a personal computer and a portable information terminal.